

Title (en)

COPPER PLATING PROCESS FOR DIFFICULT TO PLATE METALS

Publication

EP 0375179 A3 19910130 (EN)

Application

EP 89312444 A 19891129

Priority

US 28999388 A 19881221

Abstract (en)

[origin: EP0375179A2] An acid copper plating bath and process for using with electropositive metals such as aluminium and tungsten is described, wherein the bath contains sulphuric acid, copper sulphate, in solution with levelling, wetting and brightening agents.

IPC 1-7

C25D 3/38; **C25D 5/30**; **C25D 5/28**

IPC 8 full level

C25D 3/38 (2006.01); **C25D 5/38** (2006.01); **C25D 5/44** (2006.01)

CPC (source: EP)

C25D 3/38 (2013.01); **C25D 5/38** (2013.01); **C25D 5/44** (2013.01)

Citation (search report)

- [A] METALOBERFLÄCHE, vol. 33, no. 1, 1979, pages 9-16; M.F.M. EL GHANDOUR et al.: "Einfluss von Harnstoff und anderen Zusätzen, sowie der Herstellungsbedingungen auf die elektrolytische Abscheidung von Kupfer aus Kupfersulfatbädern"
- [A] CHEMICAL ABSTRACTS, vol. 96, no. 24, 14th June 1982, page 531, abstract no. 207474k, Columbus, Ohio, US; & SU-A-901 363 (V.M. GOLIKOV et al.) 30-01-1982

Cited by

DE102016113641A1; FR2818294A1; CN107447239A; CN103668355A; WO2018007749A1; WO2018019321A1; US10870924B2

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 0375179 A2 19900627; **EP 0375179 A3 19910130**; **EP 0375179 B1 19940525**; DE 68915519 D1 19940630; DE 68915519 T2 19941201; JP H02232390 A 19900914; JP H0317913 B2 19910311

DOCDB simple family (application)

EP 89312444 A 19891129; DE 68915519 T 19891129; JP 30096289 A 19891121